

**Toshiba to exhibit range of new products and technologies at Embedded World 2019**

*Demonstrations on Gigabit Ethernet Automotive connectivity and new motor control solutions on show in Hall 3A, Stand 424*

**Düsseldorf, Germany, 7<sup>th</sup> February 2019** – Toshiba Electronics Europe GmbH (TEE) today announced their participation in the Embedded World 2019 exhibition. They will be showcasing a wide range of new product releases and outstanding technology solutions such as a gigabit Automotive Ethernet bridge with support for AVB/TSN, new motor control solutions for stepper motors, and a competitive solution for reducing time to market and cost for ASIC designs.

With the automotive market transitioning to higher-speed networking solutions, visitors will be able to evaluate the TC9562XBG Ethernet AVB/TSN bridge IC. The device supports the real-time networking demands of today's connected vehicles and driver assistance systems with a transfer rate of up to 1Gbps. In addition to complying with the Ethernet AVB specification it also fulfils the TSN standard, making it suitable for the industrial market as well. To support a wide variety of Ethernet-PHYs and switches, the TC9562XBG implements MII, RMI, RGMII, as well as SGMII.

Also aiming to deliver power savings while maintaining accurate control is the TB67S128FTG stepping motor driver. The device supports 1/128 microstepping, making it suitable for applications as diverse as 3D printers, cash dispensers and home appliances, while also reducing the noise generated during operation. Toshiba's AGC (Active Gain Control) technology optimizes drive current to suit the motor's required torque, thereby preventing stalling and realizing power savings. The necessary torque is enabled by the high current drive (50V / 5A) while the low on-resistance (0.25Ω) keeps heat generation to a minimum.

Engineers will also be on hand to provide support and advice to visitors looking to use the recently announced 130nm FFSA™ (Fit Fast Structured Array) manufacturing process node. Aiming primarily at industrial applications, the new FFSA™ 130nm process adds to Toshiba's current portfolio of 28, 40, and 65nm processes, thus adding another option for industrial equipment. The 130nm node process offers different master slices for up to 664kb of RAM and around 912,000 gates per device.

Embedded World 2019 runs from the 26<sup>th</sup> to the 28<sup>th</sup> February 2019 in Nuremberg, Germany and Toshiba\* can be found in Hall 3A, on Booth 424 where their technical team will be available to discuss new and existing products and answer technical questions.

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Note to the editors:

\*embedded world 2019: Toshiba Electronics Europe GmbH is co-exhibiting with Toshiba Memory Europe GmbH.

## **About Toshiba Electronics Europe**

[Toshiba Electronics Europe GmbH](#) (TEE) is the European electronic components business of [Toshiba Electronic Devices and Storage Corporation](#). TEE offers European consumers and businesses a wide variety of innovative hard disk drive (HDD) products plus semiconductor solutions for automotive, industrial, IoT, motion control, telecoms, networking, consumer and white goods applications. The company's broad portfolio encompasses integrated wireless ICs, power semiconductors, microcontrollers, optical semiconductors, ASICs, ASSPs and discrete devices ranging from diodes to logic ICs.

TEE has headquarters in Düsseldorf, Germany, with branch offices in France, Italy, Spain, Sweden and the United Kingdom providing design, manufacturing, marketing and sales. Company president is Mr. Tomoaki Kumagai

For more company information visit TEE's web site at [www.toshiba.semicon-storage.com](http://www.toshiba.semicon-storage.com).

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